	7	6	5	4	3		2	1	
	NOTES: UNLESS OTHERWISE SPECIFIED 1 Rohs Compliant Assembly Required. Assemble Per IPC—A— 2 AQUEOUS BASED CLEANING AFTER SOLDER FOR ALL COMPONE'S ROHS SOLDER PROCESS IS ACCEPTABLE. 3 ITEM IDENTIFICATION: MARK REVISION NUMBER OF THIS DRAWING	NTS IS PREFERRED, NO—CLEAN					REV DESCRIPTION O1 INITIAL RELEASE	REVISIONS DATE APRVD 07/21/2016	
В									В
				100868 BIR BIR BIR BIR BIR REV HOUSING					
				ASSEMBLY TOP					
					UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS PROPRIETARY AND TOLERANCES:	APPROVAL DESIGNER F. PRICE ENGINEER D. BRUEY	07/21/2016 1511 Sixth	SYNAPSE Ave. Suite 300, Seattle, WA 98101 206.381.0898 RINTED CIRCUIT BOARD ASSEMBLY Housing Interconnect	
					PROPRIETARY AND CONFIDENTIAL THE INFORMATION CONTAINED IN THIS DRAWING IS PROPRIETARY AND RESTRICTED. ANY REPRODUCTION IN PART OR WHOLE WITHOUT THE EXPRESS WRITTEN PERMISSION OF THE OWNER IS PROHIBITED IN MILLIMETERS TOLERANCES: .XXX ± 0.25 .XXX ± 0.127 ANGLES ± 5 °	MECH ENG A. DAHLGREN	SIZE DWG NO	600—100868 01 SHEET 1 OF 2	
	7	6	5	4	3		2	1	

